

## Dual Non-Inverting Buffer, Open Drain

The NLX2G07 MiniGate™ is an advanced high-speed CMOS dual non-inverting buffer with open drain output in ultra-small footprint.

The NLX2G07 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

### Features

- High Speed:  $t_{PD} = 2.3$  ns (Typ) @  $V_{CC} = 5.0$  V
- Low Power Dissipation:  $I_{CC} = 1$   $\mu$ A (Max) at  $T_A = 25^\circ\text{C}$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

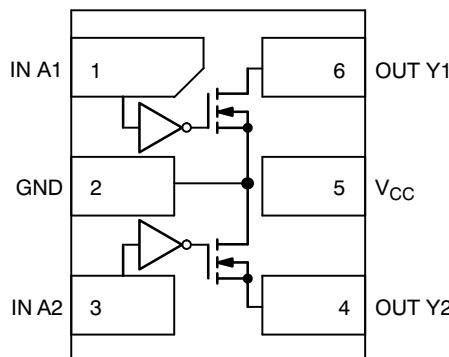


Figure 1. Pinout (Top View)

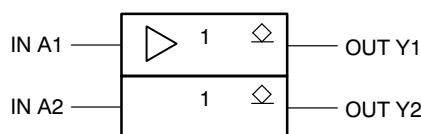


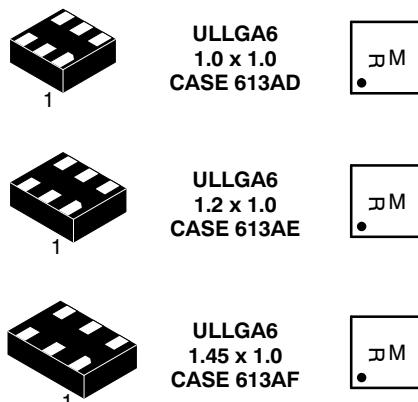
Figure 2. Logic Symbol



ON Semiconductor®

<http://onsemi.com>

### MARKING DIAGRAMS



R = Device Marking  
M = Date Code

### PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V <sub>CC</sub>
6	OUT Y1

### FUNCTION TABLE

A	Y
L	L
H	Z

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
$V_{CC}$	DC Supply Voltage	-0.5 to +7.0	V
$V_{IN}$	DC Input Voltage	-0.5 to +7.0	V
$V_{OUT}$	DC Output Voltage	-0.5 to +7.0	V
$I_{IK}$	DC Input Diode Current $V_{IN} < GND$	-50	mA
$I_{OK}$	DC Output Diode Current $V_{OUT} < GND$	-50	mA
$I_O$	DC Output Source/Sink Current	$\pm 50$	mA
$I_{CC}$	DC Supply Current Per Supply Pin	$\pm 100$	mA
$I_{GND}$	DC Ground Current per Ground Pin	$\pm 100$	mA
$T_{STG}$	Storage Temperature Range	-65 to +150	°C
$T_L$	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
$T_J$	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
$F_R$	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
$I_{LATCHUP}$	Latchup Performance Above $V_{CC}$ and Below GND at 125 °C (Note 5)	$\pm 500$	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/UESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA / JESD78.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	Positive DC Supply Voltage	1.65	5.5	V
$V_{IN}$	Digital Input Voltage	0	5.5	V
$V_{OUT}$	Output Voltage	0	5.5	V
$T_A$	Operating Free-Air Temperature	-55	+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS  
查閱NLX2G07CMAX10G datasheet

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25 °C			T <sub>A</sub> = +85°C		T <sub>A</sub> = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V <sub>IH</sub>	Low-Level Input Voltage		1.65– 1.95	0.75 x V <sub>CC</sub>			0.75 x V <sub>CC</sub>		0.75 x V <sub>CC</sub>		V
			2.3 to 5.5	0.70 x V <sub>CC</sub>			0.70 x V <sub>CC</sub>		0.70 x V <sub>CC</sub>		
V <sub>IL</sub>	Low-Level Input Voltage		1.65– 1.95			0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>	V
			2.3 to 5.5			0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>	
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 50 μA	1.65– 5.5			0.1		0.1		0.1	V
			V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 4 mA I <sub>OL</sub> = 8 mA I <sub>OL</sub> = 12 mA I <sub>OL</sub> = 16 mA I <sub>OL</sub> = 24 mA I <sub>OL</sub> = 32 mA	1.65 2.3 2.7 3.0 3.0 4.5	0.08 0.2 0.22 0.28 0.38 0.42	0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55	
I <sub>LKG</sub>	Z-State Output Leakage Current	V <sub>IN</sub> = V <sub>IH</sub> , V <sub>OUT</sub> = V <sub>CC</sub> or GND	5.5			±5.0		±10		±10	μA
I <sub>IN</sub>	Input Leakage Current	0 ≤ V <sub>IN</sub> ≤ 5.5 V	0 to 5.5			±0.1		±1.0		±1.0	μA
I <sub>OFF</sub>	Power Off Input Leakage Current	0 ≤ V <sub>IN</sub> , V <sub>OUT</sub> ≤ 5.5 V	0			1.0		10		10	μA
I <sub>CC</sub>	Quiescent Supply Current	0 ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>	5.5			1.0		10		10	μA

Symbol	Parameter	$V_{CC}$ (V)	Test Condition	$T_A = 25 \text{ }^\circ\text{C}$			$T_A = -55 \text{ }^\circ\text{C}$ to $+125 \text{ }^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	
$t_{PZL}$	Propagation Delay (Figures 3 and 4)	1.65–1.95	$R_L = R_1 = 5000 \Omega$ , $C_L = 15 \text{ pF}$	1.8	5.3	11.5	1.8	12	ns
		2.3–2.7	$R_L = R_1 = 500 \Omega$ , $C_L = 50 \text{ pF}$	1.2	3.7	5.8	1.2	6.4	
		3.0–3.6	$R_L = R_1 = 500 \Omega$ , $C_L = 50 \text{ pF}$	0.8	2.9	4.4	0.8	4.8	
		4.5–5.5	$R_L = R_1 = 500 \Omega$ , $C_L = 50 \text{ pF}$	0.5	2.3	3.5	0.5	3.9	
$t_{PLZ}$	Propagation Delay (Figures 3 and 4)	1.65–1.95	$R_L = R_1 = 5000 \Omega$ , $C_L = 15 \text{ pF}$	1.8	5.3	11.5	1.8	12	ns
		2.3–2.7	$R_L = R_1 = 500 \Omega$ , $C_L = 50 \text{ pF}$	1.2	2.8	5.8	1.2	6.4	
		3.0–3.6	$R_L = R_1 = 500 \Omega$ , $C_L = 50 \text{ pF}$	0.8	2.1	4.4	0.8	4.8	
		4.5–5.5	$R_L = R_1 = 500 \Omega$ , $C_L = 50 \text{ pF}$	0.5	1.4	3.5	0.5	3.9	
$C_{IN}$	Input Capacitance	5.5	$V_{IN} = 0 \text{ V}$ or $V_{CC}$		2.5				pF
$C_{OUT}$	Output Capacitance	5.5	$V_{IN} = 0 \text{ V}$ or $V_{CC}$		4				pF
$C_{PD}$	Power Dissipation Capacitance (Note 6)	3.3 5.5	10 MHz $V_{IN} = 0 \text{ V}$ or $V_{CC}$		4				pF

6.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation  $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no-load dynamic power consumption:  $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$ .

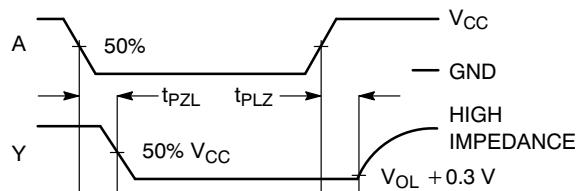
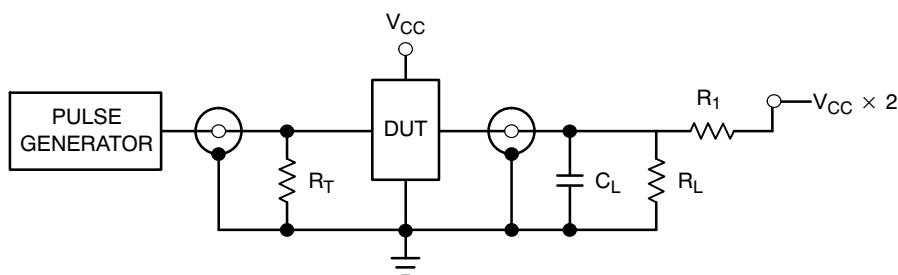


Figure 3. Switching Waveforms



$R_T = Z_{OUT}$  of pulse generator (typically  $50 \Omega$ )

Figure 4. Test Circuit

## NLX2G07

### OPERATING INFORMATION 查询“NLX2G07CMX1TCG”供应商

Device	Package	Shipping <sup>†</sup>
NLX2G07AMX1TCG	ULLGA6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G07BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G07CMX1TCG	ULLGA6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

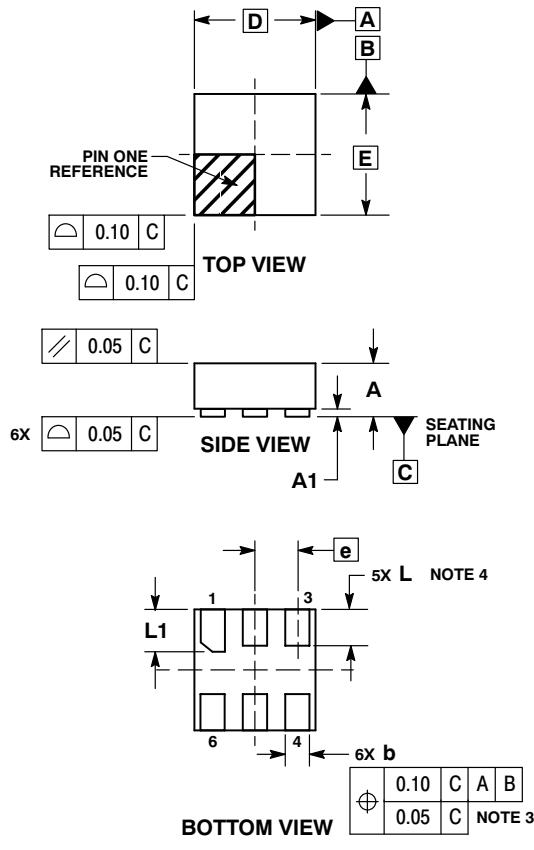
[查询"NLX2G07CMX1TCG"供应商](#)

## PACKAGE DIMENSIONS

ULLGA6 1.0x1.0, 0.35P

CASE 613AD-01

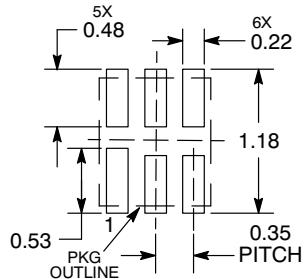
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## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

MOUNTING FOOTPRINT  
SOLDERMASK DEFINED\*

DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

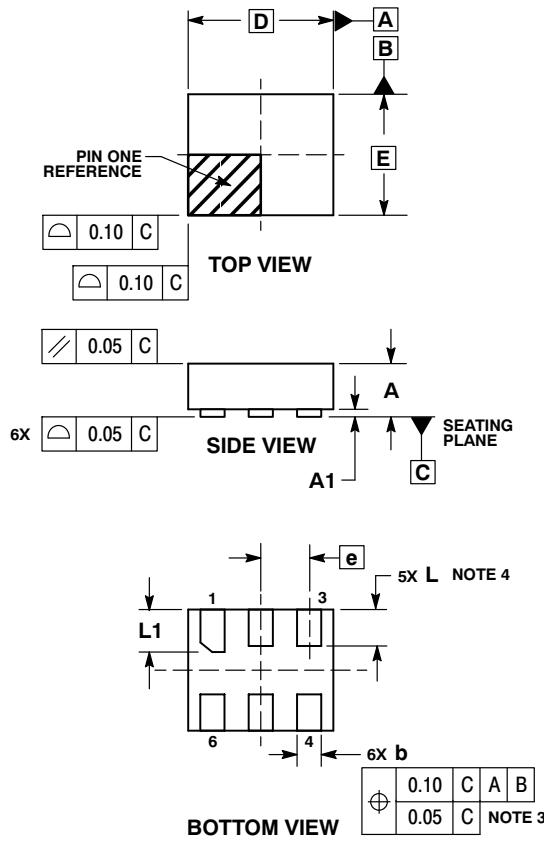
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## PACKAGE DIMENSIONS

ULLGA6 1.2x1.0, 0.4P

CASE 613AE-01

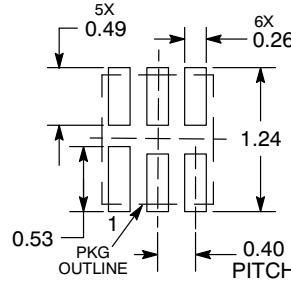
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MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.35	0.45

MOUNTING FOOTPRINT  
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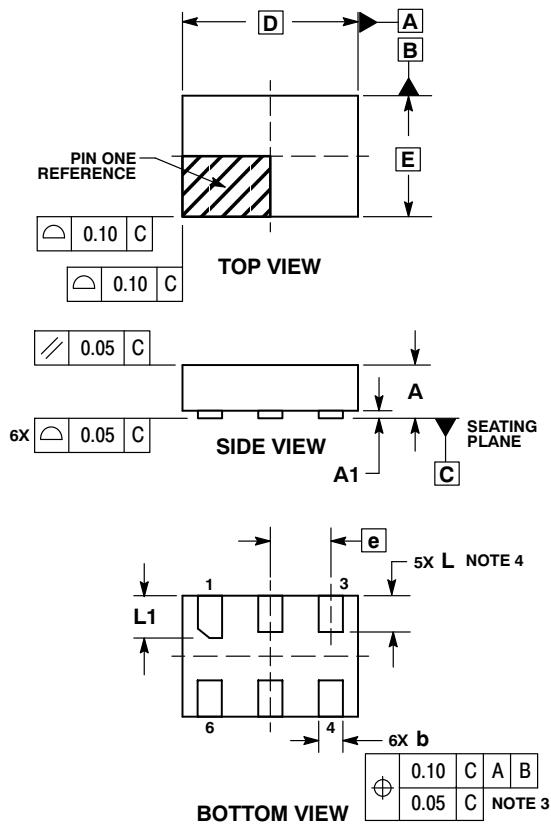
[查询"NLX2G07CMX1TCG"供应商](#)

## PACKAGE DIMENSIONS

## ULLGA6 1.45x1.0, 0.5P

CASE 613AF-01

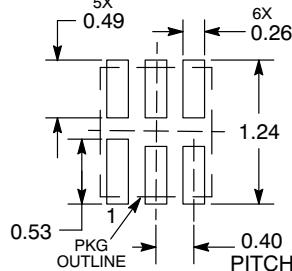
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DIM	MIN	MAX	
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A1	0.00	0.05	
b	0.15	0.25	
D	1.45	BSC	
E	1.00	BSC	
e	0.50	BSC	
L	0.25	0.35	
L1	0.30	0.40	

MOUNTING FOOTPRINT  
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